

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00772	3.23	0.11628
	Doped silicon	Silicon (Si)	7440-21-3	0.23144	96.77	3.48372
Subtotal				0.23916	100	3.6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02893	10.0	0.43546
	Silver alloy	Silver (Ag)	7440-22-4	0.00579	2.0	0.08709
	Lead alloy	Lead (Pb)	7439-92-1	0.25458	88.0	3.83201
Subtotal				0.2893	100	4.35456
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27958	100.0	4.20829
	Subtotal				0.27958	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00976	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00651	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00976	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03579	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.47711	99.81	488.8594
Subtotal				32.53893	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32221	100.0	4.85
	Subtotal				0.32221	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.30647	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.72797	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46432	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19899	0.3	2.99532
	Polymer	Epoxy resin system		6.63308	10.0	99.844
Subtotal				66.33083	100	998.44
Total				100.00001	100	1505.24286

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